

Title of Change:	PCN Update Notice - Cancellation of IPCN22454X.				
Proposed First Ship date:	1 February 2019				
Contact Information:	Contact your local ON Semiconductor Sales Office or < <u>wirasa.nontharith@onsemi.com</u> >				
Samples:	Contact your local ON Semiconductor Sales Office or < <u>PCN.Samples@onsemi.com</u> > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN)sentto customers. IPCNs are typically issued 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >				
Change Part Identification:	Date code will identify unit with this change.				
Change Category:	☐ Wafer Fab Change				
Change Sub-Category(s):					
Manufacturing Site Addi		Datasheet/Product Doc change			
Manufacturing Site Trans	ifer Product specific change	Shipping/Packaging/Marking			
Manufacturing Process Change		Other:			
Sites Affected:	ON Semiconductor Sites: NONE	External Foundry/Subcon Sites: Sub-con Thailand			
Description and Purpose:					
This Update Notice announces to customers the cancellation of IPCN22454X due to removal of affected OPNs (Orderable Part Number) from the List of Affected Parts, selection of new Qualification Vehicles and run Reliabity again.					
IPCN22454X previously announced its customers the qualification of Sub-con Thailand for the assembly changing the Die Attach Material from Epoxy Dispense (QMI519) to CDAF215. This is to improve the epoxy fillet height to meet customer requirement and also improve DA quality at assembly process (no epoxy overflow, bridging, fillet height out, epoxy on die, epoxy on lead, epoxy void).					
	Before Change Description	After Change Description			
Die Attac	ch Epoxy Dispense (QMI519)	CDAF215			
There is no product marking change as a result of this change.					



QV DEVICE NAME: 74LVTH125MX RMS: 042578 PACKAGE: F456 | SOIC14

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=145°C, 100 % max rated Vcc	504 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
HAST-PC	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs

List of Affected Parts:

Part Number	Qualification Vehicle
74LVTH125MX	
MM74HC164MX	
74LCX00MX	
74LCX08MX	
74LCX125MX	
74LCX07MX	
74ACT04SCX	74LVTH125MX (QV1 Big die size) MM74HC08MX (QV2 Small die size)
74VHC04MX	
74VHC14MX	
MM74HC125MX	
MM74HC02MX	
74VHC00MX	
MM74HC08MX	
MM74HC32MX	
74VHCT08AMX	



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
74ACT04SCX		74LVTH125MX,
		MM74HC08MX
74LCX00MX		74LVTH125MX,
		MM74HC08MX
74LCX07MX		74LVTH125MX,
		MM74HC08MX
74LCX08MX		74LVTH125MX,
		MM74HC08MX
74LCX125MX		74LVTH125MX,
		MM74HC08MX
74LVTH125MX		74LVTH125MX,
		MM74HC08MX
74VHC00MX		74LVTH125MX,
		MM74HC08MX
74VHC04MX		74LVTH125MX,
		MM74HC08MX
74VHC14MX		74LVTH125MX,
		MM74HC08MX
74VHCT08AMX		74LVTH125MX,
		MM74HC08MX
MM74HC02MX		74LVTH125MX,
		MM74HC08MX
MM74HC08MX		74LVTH125MX,
		MM74HC08MX
MM74HC125MX		74LVTH125MX,
		MM74HC08MX
MM74HC164MX		74LVTH125MX,
		MM74HC08MX
MM74HC32MX		74LVTH125MX,
		MM74HC08MX